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To the Honorable Commissioner o … lease record the attached original documents or copy thereof.

1 Name of conveying party(ies):

Yu-Te Hsieh
Shyh-Ming Chang
Wen-Ti Lin

2 Name and address of receiving party(ies):

Industrial Technology Research Institute
Room 51-103, TTSC/B100
195 Section 4, Chung Hsing Road
Chutung, Hsinchu, Taiwan 310 R.O.C.

J1011 U.S. PTO
10/152468
05/21/02

Additional name(s) & address(es) attached ☐ Yes ☒ No

3 Nature of conveyance:
■ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other:
Execution Date: March 29, 2002

4 Application number(s) or patent number(s): 10152468

If this document is being filed together with a new application, the execution date of the application is: 03-29-02

A. Patent Application No(s).

B. Patent No(s)

Additional numbers attached? ☐ Yes ☒ No

5 Name and address of party to whom correspondence concerning document should be mailed:

RANDY W. TUNG
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05/24/2002 HLE333 00000008 10152468
03 FC:581 40.00 OP

6 Total number of applications and patents involved: 1

7 Total fee (37 CFR 3.41) $40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Randy W. Tung
Name of Person Signing
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Signature

May 21, 2002
Date

Total number of pages including cover sheet, attachments, and document: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

64,600-085
90033

ASSIGNMENT

WHEREAS, WE, YU-TE HSIEH, SHYH-MING CHANG and WEN-TI LIN have invented certain improvements in METHOD FOR BONDING IC CHIPS TO SUBSTRATES WITH NON-CONDUCTIVE ADHESIVE AND ASSEMBLIES FORMED for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar ($1.00) and other good and valuable consideration, the receipt of which is hereby acknowledged, We, YU-TE HSIEH, SHYH-MING CHANG and WEN-TI LIN, by these presents, do hereby sell, assign and transfer unto the said corporation and its assigns, for the territory of the United States of America and all foreign countries, the entire right, title and interest, including all priority rights under the International Convention associated with each country of the Union, in and to said invention as described in the patent application executed by us on the 29th day of March, 2002, preparatory to obtaining Letters Patent of the United States thereon, and in and to said application and any Letters Patent that may be granted in pursuance of said application and any divisional, continuation or continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to any patent applications which may be filed on said invention in countries foreign to the United States and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention in its own name or through its designees, including subsidiaries, related companies or assignees, under the International Convention or otherwise, and we further agree to execute all papers, including those required for the United States and foreign applications, and to perform such other proper acts as said corporation or its designees the rights herein assigned.

Yu-TE HSieh

YU-TE HSIEH

Shyh-Ming Chang

SHYH-MING CHANG

Wen-Ti Lin

WEN-TI LIN

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